

**REMARKS**

Claims 3, 8, 11 and 12 have been amended. New claims 15-17 have been added. Claim 9 has been canceled. Reconsideration and reexamination of the amended application respectfully are requested.

The Examiner rejected claims 8-12 under 35 USC 112, second paragraph as being indefinite. The rejection respectfully is traversed. The rejection is based on the assertion that the portion 25c disclosed in the specification is "the gold portion of the post including a portion facing the passivation film/resin film interface." However, that portion of the post as recited in claim 8 is supported in the specification by the portion 25a of the post, which, as illustrated in Fig. 5, is clearly in contact with the interface between the passivation layer 14 and the resin film layer 16, since it passes directly through it. Withdrawal of the rejection therefore respectfully is requested.

Independent claim 3 and depending claims 4, 6 and 14 are rejected under 35 USC §102(e) as being unpatentable over *Saimoto et al.* The rejection respectfully is traversed.

According to the Examiner, *Saimoto et al.* disclosed a first resin film at col. 6, lines 11-15. However, the resin film disclosed by *Saimoto et al.* is merely a surface protecting adhesive film that is adhered to the surface of a semiconductor wafer to prevent breakage of the wafer during the various steps of its production, and is peeled off from the wafer surface after completion of the wafer production steps. In this regard, the Examiner is referred to column 4, lines 6-7 of *Saimoto et al.* On the other hand, the first resin film of the present invention is a layer that is retained on the semiconductor substrate of the semiconductor device of the invention. To make this clearer, claim 3 has been amended to specify that the semiconductor substrate is not the wafer of *Saimoto et al.*, but rather is a substrate that is divided from a semiconductor wafer. See, for example, Fig. 3 of the present specification. Clearly, *Saimoto et al.*'s adhesive layer is removed prior to any dicing of the wafer, and it would be totally impractical to remove it afterward. Therefore, for at least this reason, claim 3 clearly is not anticipated by, or even obvious over the teaching of *Saimoto et al.* The rejection accordingly should be withdrawn as to this claim and its depending claims 4, 6, 11 and 12.

Independent claim 8 and depending claims 9 and 10 are rejected under 35 USC §102(e)

as anticipated by *Wakamiya et al.* (US Patent Publication No. 2002/0041013). Claim 9 has been canceled and incorporated in claim 8 in a form that clarifies that, designating the previously claimed gold portion of the post as a “first portion,” the post also includes a second portion made of a metal material other than gold, which is separated from the passivation film/resin film interface by the first portion. The rejection of claim 8 and the remaining depending claim 10 is inapplicable to the claims as amended.

The rejection is made based in part on an assertion that the reference discloses a gold portion of a post in direct contact with a passivation film/resin film interface. *Wakamiya et al.* relies upon an alleged disclosure in the reference of an embodiment in which the post is made entirely of gold. The Examiner states that *Wakamiya et al.* discloses a post formed entirely of gold to support his assertion that the reference teaches the claimed gold portion of the post in direct contact with the passivation film/resin film interface, and also states to support his rejection of dependent claim 9 that *Wakamiya et al.* discloses a post that includes a portion made of a metal material other than gold. Thus, two different embodiments of the post of *Wakamiya et al.* are being relied upon incorrectly to reject a claim to an impossible combination of features that clearly are not disclosed by *Wakamiya et al.* together in a single embodiment. That is, *Wakamiya et al.*'s post cannot at the same time be formed entirely of gold and have a portion made of a material other than gold. Therefore, *Wakamiya et al.* does not anticipate or even suggest the invention of amended claim 8. The rejection accordingly should be withdrawn.

New claim 15, depending from claim 8, new independent claim 16, and new claim 17 depending there claim 16 have been added to further protect the invention. For example, claim 16 is similar to claim 8 prior to the present amendment, but specifies that a protruding electrode is formed on one surface of the semiconductor substrate, and a first resin film is formed on the one surface of the semiconductor substrate so that the protruding electrode protrudes through the first resin film. This feature clearly distinguishes the invention from the teachings of *Wakamiya et al.* The Examiner, in explaining his rejection claim 8, takes the position that *Wakamiya et al.* discloses a protruding electrode at column 6, lines 11-15. However, applicant can find no such disclosure, as the reference is silent about any protruding electrode. Claim 16 therefore is

deemed clearly to be patentable over *Wakamiya et al.* New dependent claim 17, like amended claim 3, specifies that the semiconductor substrate is divided from a semiconductor wafer. The claim therefore clearly is patentable for both the reasons advanced above as to claim 16 as well as those advanced as to claim 3.

Based on the above, it is submitted that the application is in condition for allowance and such a Notice, with allowed claims 3, 4, 6, 8, 10 - 12 and 14-17, earnestly is solicited.

The amount of \$120.00 is attached in payment of the Petition for One-month Extension by way of Credit Card Form PTO-2038. Should the remittance be accidentally missing or insufficient, the Commissioner is hereby authorized to charge the fee to our Deposit Account No. 18-0002, and advise us accordingly.

Respectfully submitted,



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